



SOT949-2

plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 7 x 7 x 0.85 mm

10 June 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package type industry code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	18-9-2012

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	0.8	-	0.85	1	mm
A ₂	package height	-	-	-	-	
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	56	-	



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2. Package outline

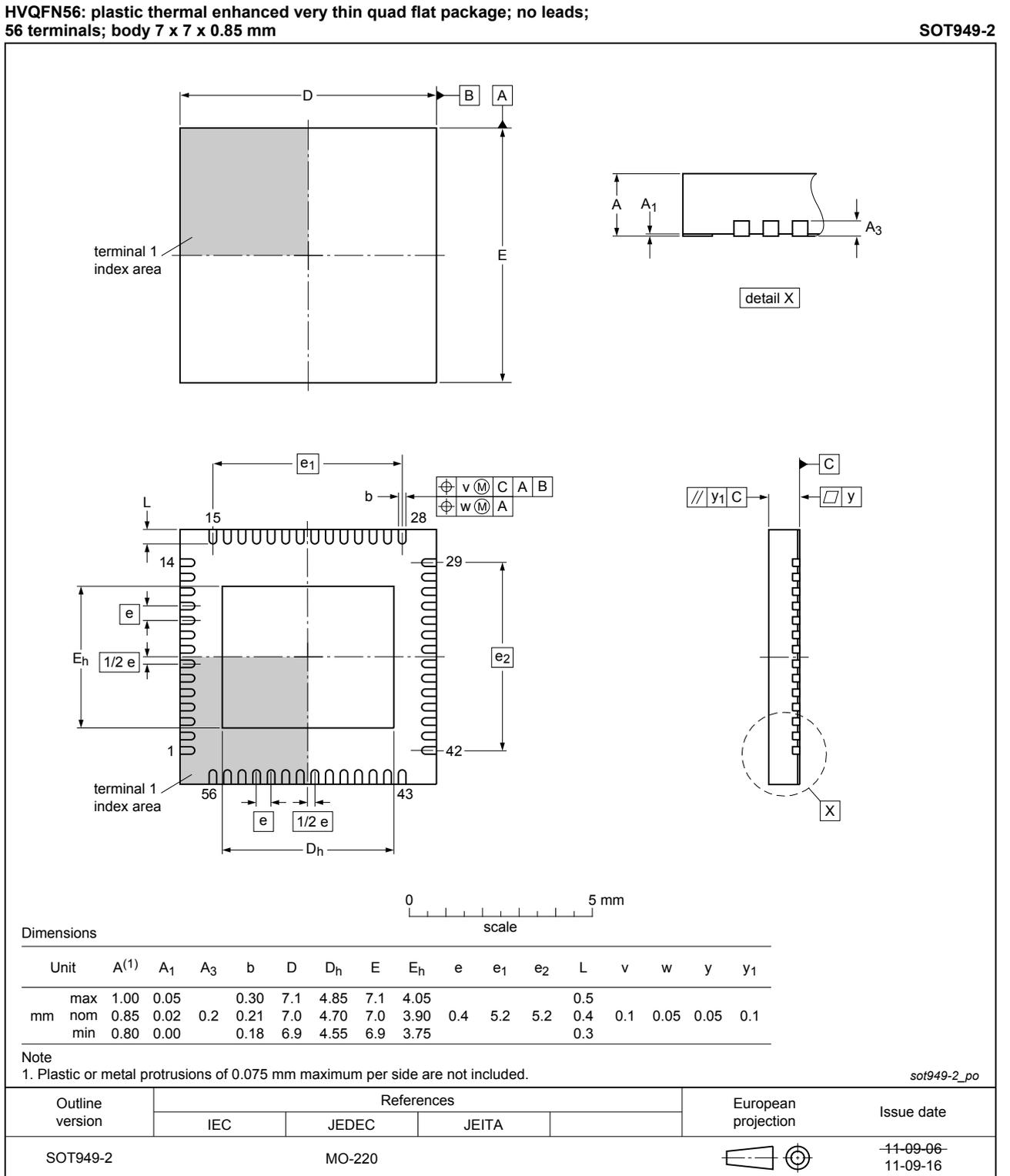


Fig. 1. Package outline HVQFN56 (SOT949-2)

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4. Legal information

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Date of release: 10 June 2016
